

## 100V N-Channel Power MOSFET

### DESCRIPTION :

- Excellent  $R_{DS(ON)}$
- Low Gate Charge
- Pb-Free Lead Plating
- RoHS compliant
- Halogen Free

$V_{DSS}$	100V
$I_D @ V_{GS}=10V$	1.9A
$R_{DS(ON)_Typ.} @ V_{GS}=10V$	105m $\Omega$

### TYPICAL APPLICATIONS :

- Load Switch
- PWM Application
- Power Management



SOT-23

### MAXIMUM RATINGS (at $T_c = 25^\circ C$ , unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		$V_{DS}$	100	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$T_c=25^\circ C$ $T_c=100^\circ C$	$I_D$	1.9 1.2	A
Pulsed Drain Current <sup>(1)</sup>		$I_{DM}$	Refer to Fig.4	A
Single Pulsed Avalanche Energy <sup>(2)</sup>		EAS	6.6	mJ
Power dissipation	$T_c=25^\circ C$ $T_c=100^\circ C$	$P_D$	0.9 0.4	W
Junction & Storage temperature Range		$T_J, T_{STG}$	-55~+150	$^\circ C$

Notes : 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. EAS condition: Starting  $T_J=25^\circ C$ ,  $V_{DD}=50V$ ,  $V_{GS}=10V$ ,  $R_G=25\Omega$ ,  $L=3mH$ ,  $I_{AS}=2.1A$ ,  $V_{DD}=0V$  during time in avalanche.

### THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient	$R_{\theta JA}$	137	$^\circ C/W$

ELECTRICAL CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = 250uA	$V_{(BR)DSS}$	100			V
Zero Gate Voltage Drain Current VDS = 80 V, VGS = 0 V,	$I_{DSS}$			1.0	uA
Gate-Source Leakage Current VGS = $\pm 20$ V, VDS = 0V	$I_{GSS}$			$\pm 100$	nA
Gate-Source threshold voltage VDS = VGS, ID = 250uA	$V_{GS(th)}$	1.3	1.9	2.5	V
Drain-Source On-State Resistance VGS = 10V, ID = 2A VGS = 4.5V, ID = 1A	$R_{DS(on)}$		105 136	136 177	m $\Omega$
Gate Resistance f=1MHz	$R_g$		1.1		$\Omega$
Input capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{iss}$		137	205	pF
Output capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{oss}$		51	76	pF
Reverse transfer capacitance f=1MHz, VDS=50 V, VGS=0 V	$C_{rss}$		4.0		pF
Total Gate Charge VDS= 50V, ID= 2A, VGS=0 to 10V	$Q_G$		3.2		nC
Gate to Source Charge VDS= 50V, ID= 2A, VGS=0 to 10V	$Q_{GS}$		0.8		nC
Gate to Drain Charge VDS= 50V, ID= 2A, VGS=0 to 10V	$Q_{GD}$		0.6		nC
Turn-on delay time VDS= 50V, VGS= 10V, ID=2A, RGEN=3 $\Omega$	td (ON)		2.2		ns
Rise time VDS= 50V, VGS= 10V, ID=2A, RGEN=3 $\Omega$	tr		3.0		ns
Turn-off delay time VDS= 50V, VGS= 10V, ID=2A, RGEN=3 $\Omega$	td (OFF)		6.5		ns
Fall time VDS= 50V, VGS= 10V, ID=2A, RGEN=3 $\Omega$	tf		2.2		ns

Body Diode CHARACTERISTICS (at  $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Maximum Continuous Body Diode Forward Current	$I_S$			1.9	A
Maximum Pulsed Body Diode Forward Current	$I_{SM}$			7.6	A
Body Diode Forward Voltage $V_{GS} = 0V, I_S = 2A$	$V_{SD}$			1.2	V
Revers Recovery Time $I_F = 2A, di/dt = 100A/\mu s$	$T_{rr}$	14	23	34	ns
Revers Recovery Charge $I_F = 2A, di/dt = 100A/\mu s$	$Q_{rr}$		11.5		nC

Typical Performance Characteristics

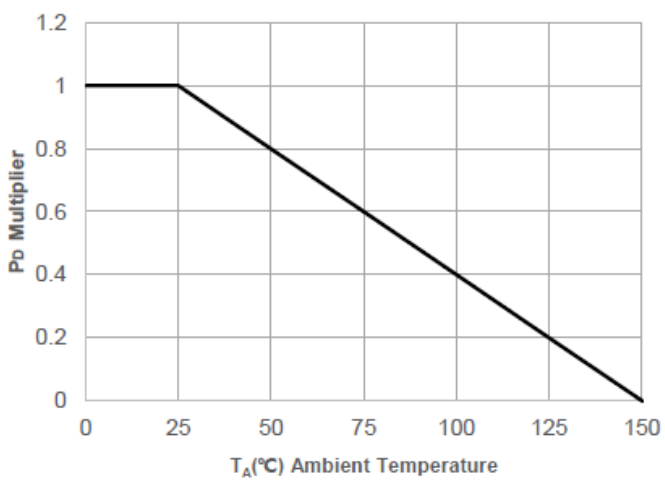


Figure 1. Power De-rating

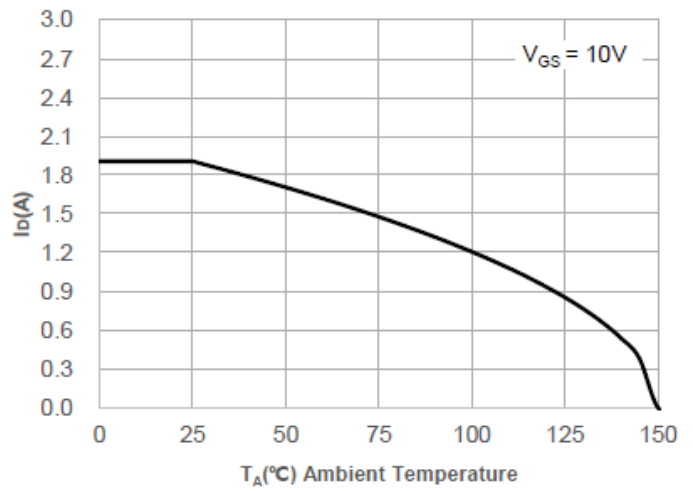


Figure 2. Current De-rating

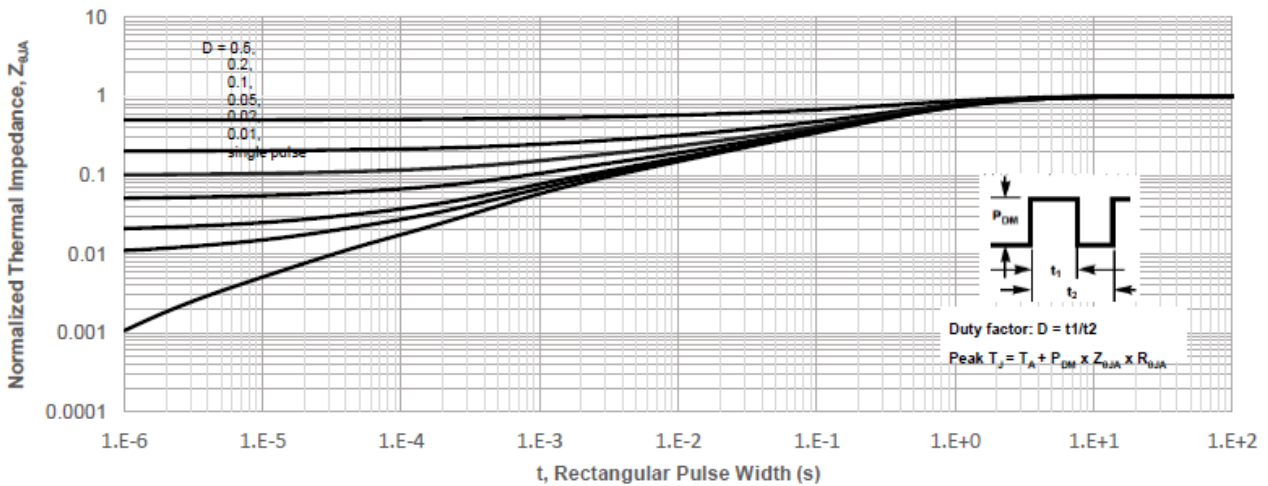


Figure 3. Normalized Maximum Transient Thermal Impedance

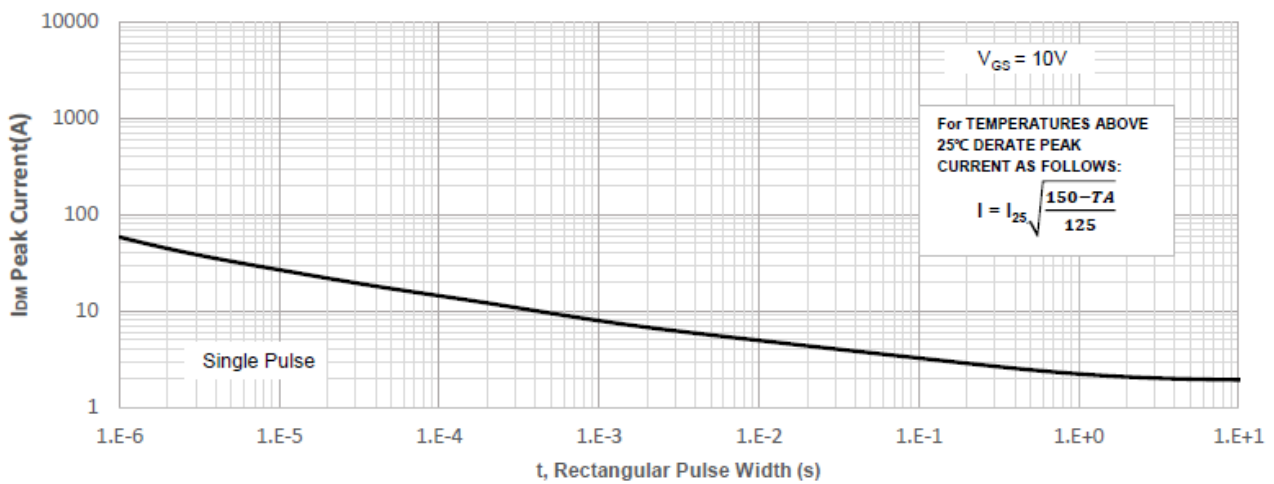


Figure 4. Peak Current Capacity

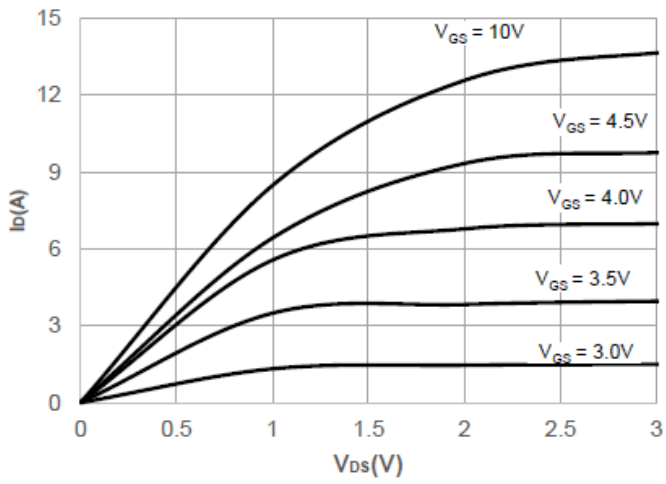


Figure 5. Output Characteristics

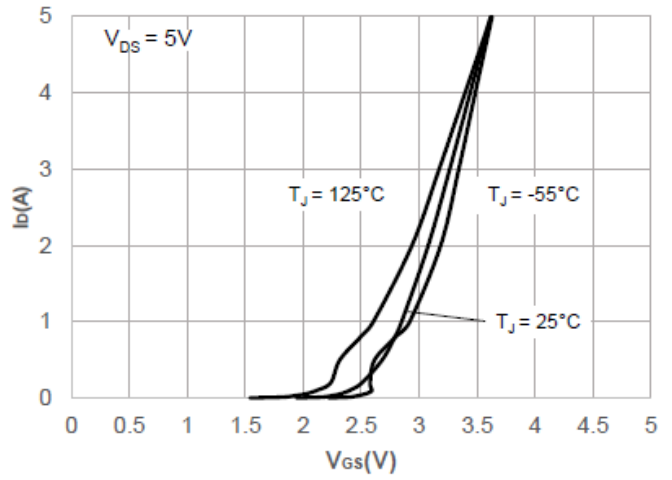


Figure 6. Typical Transfer Characteristics

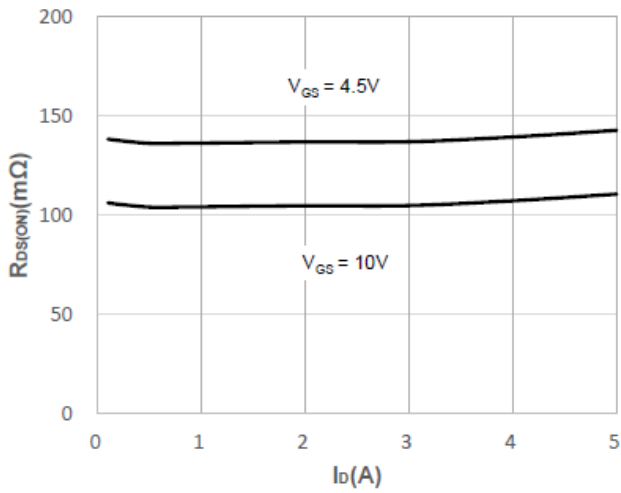


Figure 7. On-resistance vs. Drain Current

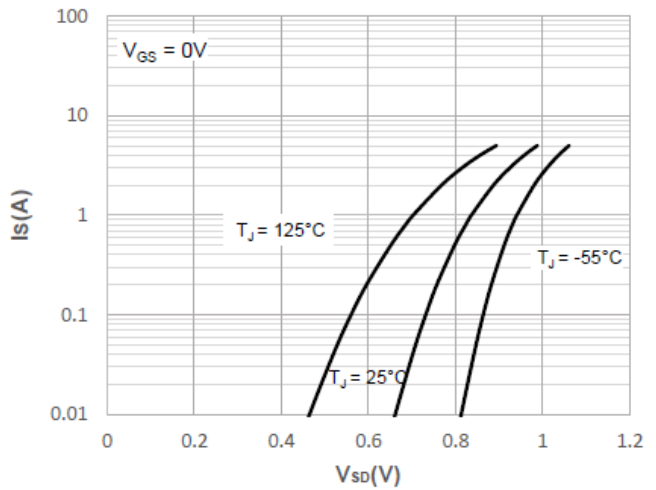


Figure 8. Body Diode Characteristics

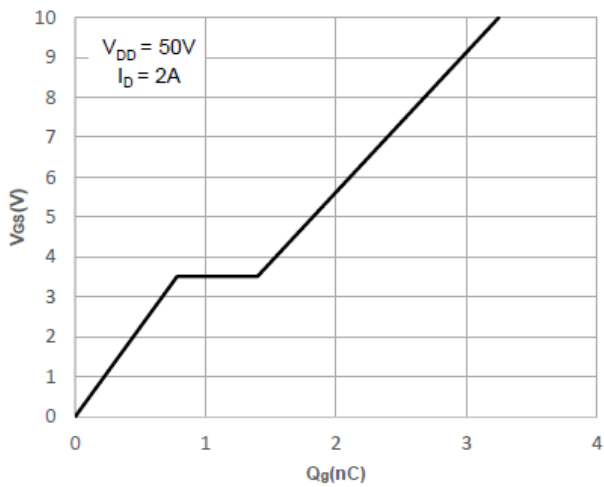


Figure 9. Gate Charge Characteristics

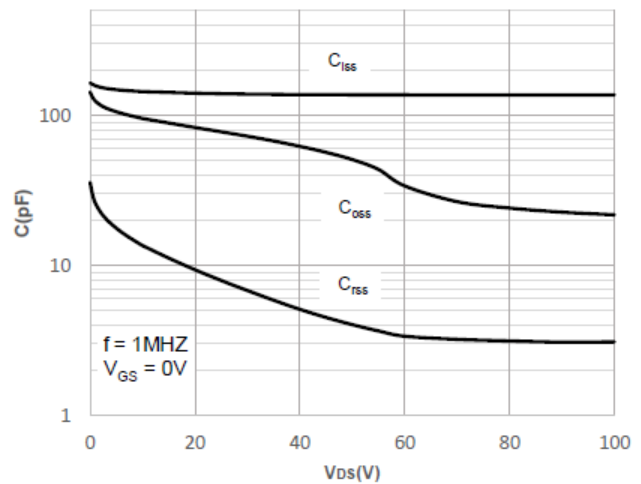


Figure 10. Capacitance Characteristics

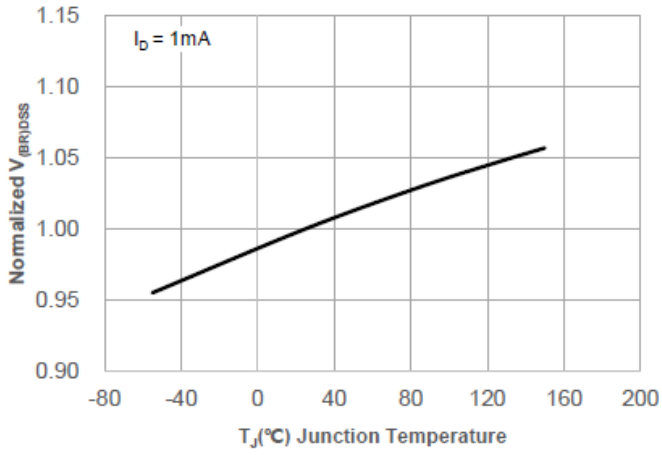


Figure 11. Normalized Breakdown voltage vs. Junction Temperature

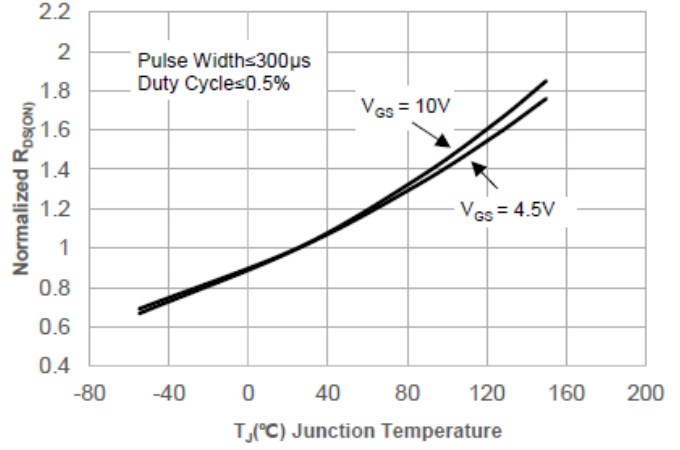


Figure 12. Normalized on Resistance vs. Junction Temperature

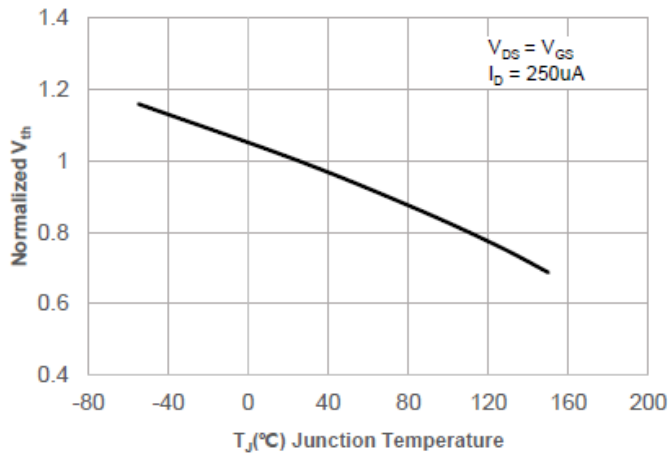


Figure 13. Normalized Threshold Voltage vs. Junction Temperature

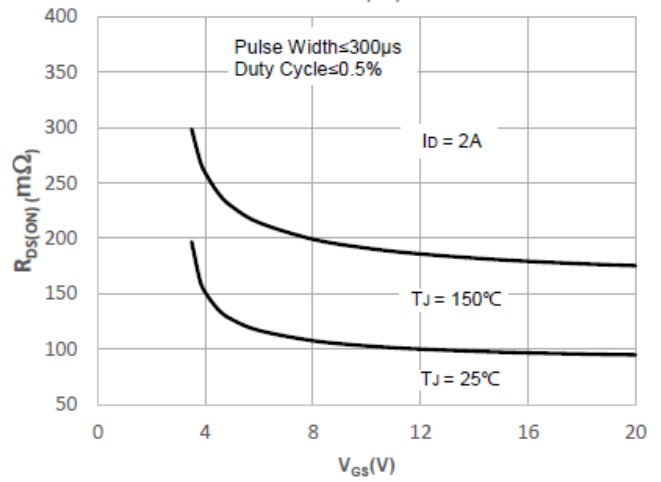


Figure 14.  $R_{DS(ON)}$  vs.  $V_{GS}$

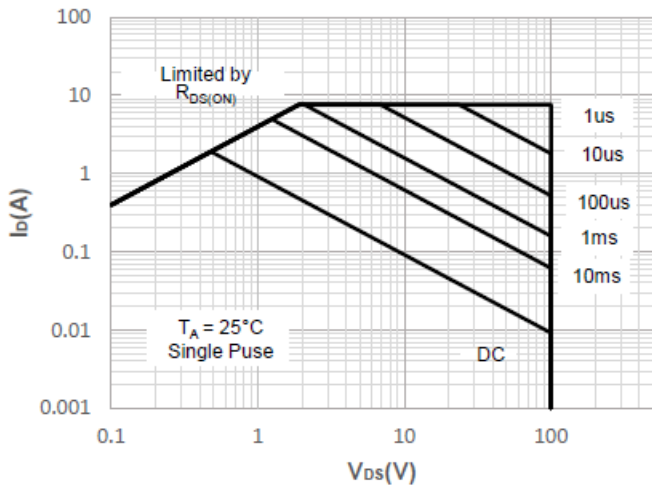
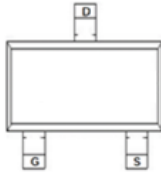
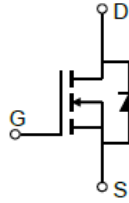


Figure 15. Maximum Safe Operating Area

·Circuit diagram

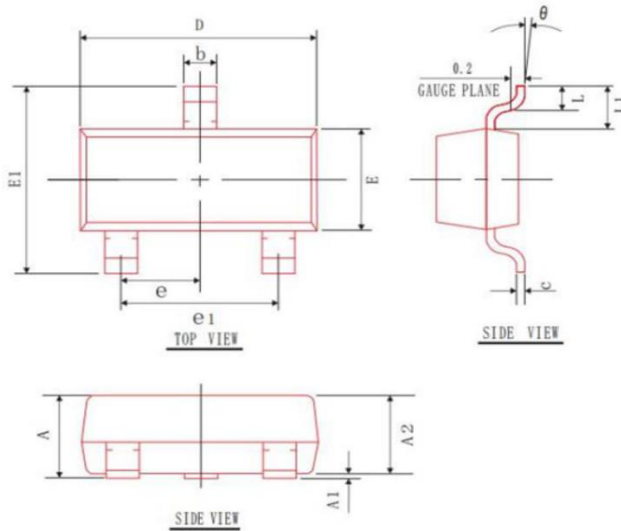


Pin Assignment



Schematic Diagram

·Package outlines : Dimensions in (mm)



COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	0.90	1.05	1.20
A1	0.00	0.05	0.10
A2	0.90	1.00	1.10
b	0.30	0.40	0.50
c	0.08	0.10	0.15
D	2.80	2.90	3.00
E	1.20	1.30	1.40
E1	2.30	2.40	2.50
L	0.30	0.40	0.50
$\theta$	0°	5°	10°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		

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